

Product Data Sheet

Flip-Chip Flux WS-446

Features

- Designed for flip-chip dipping applications
- Tackiness suitable for holding large die during assembly
- Bubble-free packaging
- Red color for ease of detection

Introduction

Flip-Chip Flux WS-446 is a water soluble flip-chip dipping flux which has an activator system powerful enough to promote wetting on the most demanding substrate metallizations. The flux is a distinctive red color, which aids automated level-sensing equipment and also enhances visual inspection.

Properties

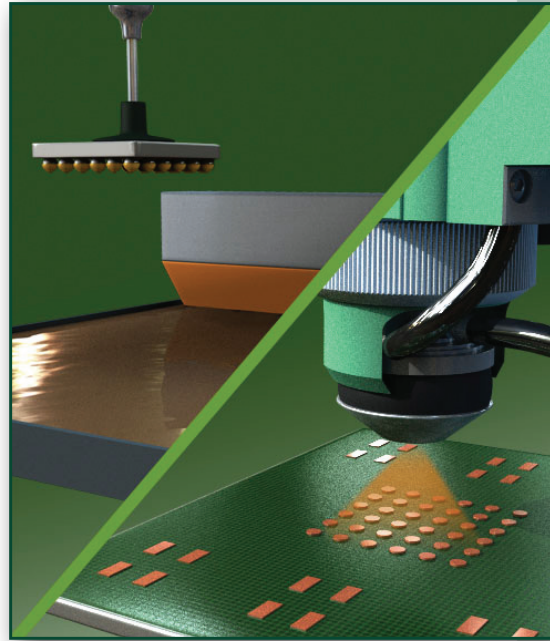
Property	Value	Test Method
Flux Classification:	H1	J-STD-004 (IPC-TM-650: 2.3.32 and 2.3.33)
Typical Viscosity:	9kcps	Brookfield HB DVII+-CP (5rpm)
SIR (ohms, after cleaning):	Pass (>10 ⁹ after 7 days @ 85°C & 85% RH)	J-STD-004 (IPC-TM-650: 2.6.3.3 IPC-B-24)
Typical Acid Value:	71mg KOH/g	Titration
Typical Tack Strength:	570g	J-STD-005 (IPC-TM-650: 2.4.44)
Shelf Life:	6 months (-20°C to +5°C)	Viscosity change / microscope examination

All information is for reference only. Not to be used as incoming product specifications.

Application

WS-446 is intended to be used in a nitrogen reflow environment of 50ppm oxygen or less. **WS-446** can be used on many surface finishes including immersion Ag, Cu, and Ni. These surfaces can be soldered with Sn/Pb or Pb-free alloys.

Flux depth should be set to approximately 30-50% of the flip-chip solder bump height.



Cleaning

WS-446 residue can be cleaned with DI water, or water with an added cleaner. Ideal conditions for spray-cleaning: 25°C (room temperature) or higher for >1 minute at >60psi.

Packaging

WS-446 is available in 10cc and 30cc syringes.



OVER→

Form No. 98684 R0

www.indium.com

askus@indium.com

ASIA: Singapore, Cheongju: +65 6268 8678
 CHINA: Suzhou, Shenzhen, Liuzhou: +86 (0)512 628 34900
 EUROPE: Milton Keynes, Torino: +44 (0) 1908 580400
 USA: Utica, Clinton, Chicago: +1 315 853 4900



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Storage

For maximum shelf life **WS-446** syringes and cartridges should be stored tip down. Storage temperatures should not exceed 30°C. After removing from cold storage, **WS-446** should be allowed to stand for at least 4 hours at room temperature before using.

Technical Support

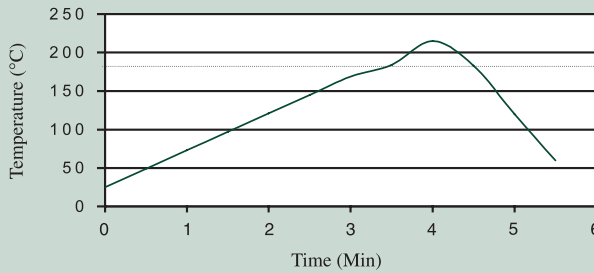
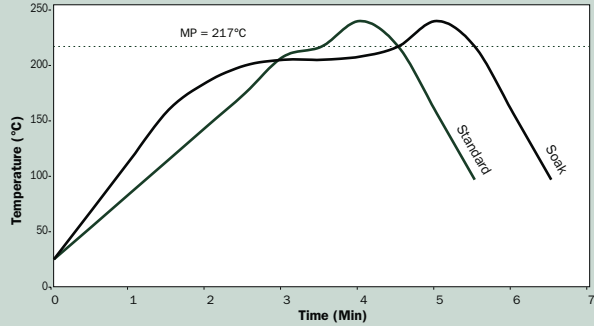
Indium Corporation sets the industry standard in providing rapid response, on-site technical support for our customers worldwide. Indium's team of Technical Support Engineers can provide expertise in all aspects of Materials Science and Semiconductor Packaging process applications.

Material Safety Data Sheets

The MSDS for this product can be found online at <http://www.indium.com/techlibrary/msds.php>

Reflow

Recommended Profile:



Peak reflow temperature should be <350°C in a nitrogen atmosphere (<50ppm O₂), with a linear ramp up to 30°C above liquidus temperature. These profiles are recommended to the user as starting points, and should be optimized by the user to meet their individual process needs.

This product data sheet is provided for general information only. It is not intended, and shall not be construed, to warrant or guarantee the performance of the products described which are sold subject exclusively to written warranties and limitations thereon included in product packaging and invoices.

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